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(54) **Title**: PANELIZED PACKAGING WITH TRANSFERRED DIELECTRIC

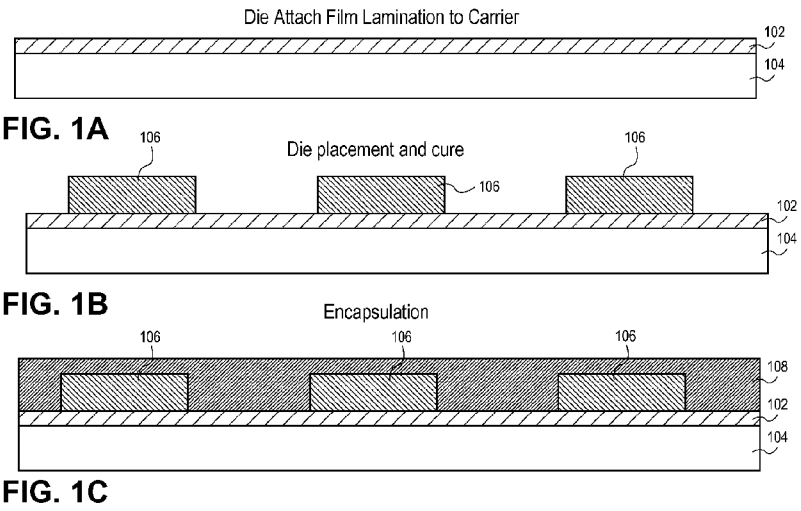


FIG. 1A

FIG. 1B

FIG. 1C

(57) **Abstract**: A method of panelized packaging is described in which a plurality of die units are placed on a dielectric film. The dielectric film is then cured to lock the plurality of die units in place, which are then encapsulated. The cured dielectric film is then patterned utilizing a mask-less patterning technique.

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